What is claimed is:

1. A module comprising:

a duplexer including an antenna terminal;

a first wiring connecting the antenna terminal to an antenna;

a second wiring coupled to the antenna terminal without the first wiring; and

an inductor coupled to the second wiring.

2. The module according to claim 1, wherein

the duplexer is mounted on a substrate, and

the first wiring and the second wiring are located in the substrate.

3. The module according to claim 2, wherein

the substrate is a multilayered substrate including conductive layers that are stacked, and

the first wiring and the second wiring are located in different conductive layers of the conductive layers.

4. The module according to any one of claims 1 to 3, wherein

the duplexer includes an acoustic wave filter, and

the acoustic wave filter includes an IDT.

5. The module according to any one of claims 2 to 4, wherein

the duplexer is flip-chip mounted on an upper surface of the substrate,

the antenna terminal is coupled to an antenna pad located on the upper surface of the substrate,

the first wiring is coupled to the antenna pad, and

the second wiring is coupled to the antenna pad without the first wiring.

6. The module according to any one of claims 1 to 5, wherein

a first end of the inductor is coupled to the second wiring, and a second end of the inductor is grounded.

7. The module according to any one of claims 2 to 6, wherein

the inductor is included in a chip component mounted on the substrate.

## CLAIMS

What is claimed is:

1. A module comprising:

a duplexer including an antenna terminal;

a first wiring connecting the antenna terminal to an antenna;

a second wiring coupled to the antenna terminal without the first wiring; and

an inductor coupled to the second wiring,

wherein

the duplexer is mounted on a substrate,

the first wiring and the second wiring are located in the substrate, and

the inductor is included in a chip component mounted on the substrate.

2. The module according to claim 1, wherein

the substrate is a multilayered substrate including conductive layers that are stacked, and

the first wiring and the second wiring are located in different conductive layers of the conductive layers.

3. The module according to claim 1, wherein

the duplexer includes an acoustic wave filter, and

the acoustic wave filter includes an IDT.

4. The module according to claim 1, wherein

the duplexer is flip-chip mounted on an upper surface of the substrate,

the antenna terminal is coupled to an antenna pad located on the upper surface of the substrate,

the first wiring is coupled to the antenna pad, and

the second wiring is coupled to the antenna pad without the first wiring.

5. The module according to claim 1, wherein

a first end of the inductor is coupled to the second wiring, and a second end of the inductor is grounded.

6. A module comprising:

a duplexer including an antenna terminal;

a first wiring connecting the antenna terminal to an antenna;

a second wiring coupled to the antenna terminal without the first wiring; and

an inductor coupled to the second wiring,

wherein

the substrate is a multilayered substrate including insulating layers and conductive layers respectively located on surfaces of the insulating layers,

the first wiring and the second wiring are located in different conductive layers of the conductive layers and extend at a surface direction of the insulating layers, and

a via wiring that penetrates through an insulating layer located between the different conductive layers connects the first wiring and the second wiring.

7. A module comprising:

a duplexer including an antenna terminal;

a first wiring connecting the antenna terminal to an antenna;

a second wiring coupled to the antenna terminal without the first wiring; and

an inductor coupled to the second wiring,

wherein

the duplexer is flip-chip mounted on an upper surface of the substrate,

the antenna terminal is coupled to an antenna pad located on the upper surface of the substrate,

the first wiring is coupled to the antenna pad,

the second wiring is coupled to the antenna pad without the first wiring, and

the first wiring and the second wiring are located on the same surface of an insulating layer included in the substrate.